TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS IV)

# **TPCS8104**

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance:  $R_{DS}$  (ON) = 8.1 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 23 \text{ S} (typ.)$
- Low leakage current:  $I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -30 \ V)$
- Enhancement-mode:  $V_{th}$  = -0.8 to -2.0 V (VDS = -10 V, ID = -1 mA)

#### Maximum Ratings (Ta = 25°C)

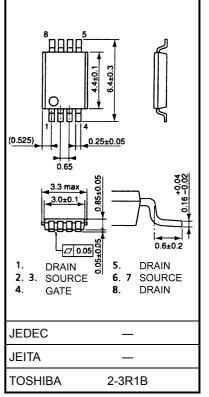
next page.

caution.

| Characteri                   | stics                       | Symbol           | Rating     | Unit |
|------------------------------|-----------------------------|------------------|------------|------|
| Drain-source voltage         |                             | V <sub>DSS</sub> | -30        | V    |
| Drain-gate voltage (R        | <sub>GS</sub> = 20 kΩ)      | V <sub>DGR</sub> | -30        | V    |
| Gate-source voltage          |                             | V <sub>GSS</sub> | ±20        | V    |
| Drain current                | DC (Note 1)                 | ۱ <sub>D</sub>   | -11        | А    |
| Dialiteuren                  | Pulse (Note 1)              | I <sub>DP</sub>  | -44        |      |
| Drain power dissipatio       | n (t = 10 s)<br>(Note 2a)   | PD               | 1.1        | W    |
| Drain power dissipatio       | n (t = 10 s)<br>(Note 2b)   | PD               | 0.6        | W    |
| Single pulse avalanch        | e energy<br>(Note 3)        | E <sub>AS</sub>  | 31.5       | mJ   |
| Avalanche current            |                             | I <sub>AR</sub>  | -11        | А    |
| Repetitive avalanche e<br>(N | energy<br>lote 2a) (Note 4) | E <sub>AR</sub>  | 0.11       | mJ   |
| Channel temperature          |                             | T <sub>ch</sub>  | 150        | °C   |
| Storage temperature r        | ange                        | T <sub>stg</sub> | –55 to 150 | °C   |

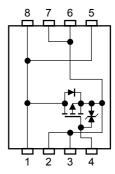
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the

This transistor is an electrostatic sensitive device. Please handle with



Weight: 0.035 g (typ.)

### **Circuit Configuration**



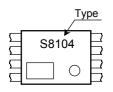
Unit: mm

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### **Thermal Characteristics**

| Characteristics   | Symbol                 | Max | Unit |
|---|------------------------|-----|------|
| Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a) | R <sub>th (ch-a)</sub> | 114 | °C/W |
| Thermal resistance, channel to ambient<br>(t = 10 s) (Note 2b)        | R <sub>th (ch-a)</sub> | 208 | °C/W |

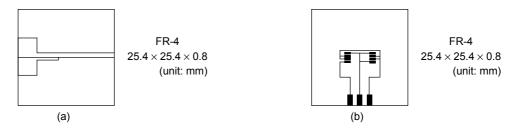
### Marking (Note 5)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

#### Note 2:

(a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



Note 3:  $V_{DD} = -24 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.2 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = -11 A

- Note 4: Repetitive rating: pulse width limited by maximum channel temperature
- Note 5: on lower right of the marking indicates Pin 1.

shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

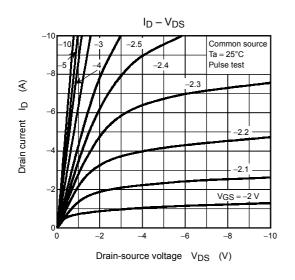
Electrical Characteristics (Ta = 25°C)

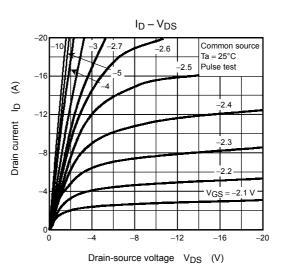
| Characteristics   |               | Symbol   | Test Condition  | Min        | Тур. | Max  | Unit |
|---|---------------|--|---|------------|------|------|------|
| Gate leakage current                                      |               | I <sub>GSS</sub>                                       | $V_{GS}=\pm 16~V,~V_{DS}=0~V$                                     | _          |      | ±10  | μA   |
| Drain cut-OFF current                                     |               | I <sub>DSS</sub>                                       | $V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$            | _          |      | -10  | μA   |
| Drain-source breakdo                                      | wn voltage    | V (BR) DSS   | $I_D = -10$ mA, $V_{GS} = 0$ V                                    | -30        | _    | _    | V    |
| Drain-source breakuo                                      | wir voltage   | V (BR) DSX   | $I_D = -10$ mA, $V_{GS} = 20$ V                                   | ±10<br>−10 | v    |      |      |
| Gate threshold voltage                                    |               | V <sub>th</sub>  | $V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA}$           | -0.8       |      | -2.0 | V    |
| Drain-source ON resistance<br>Forward transfer admittance |               | R <sub>DS (ON)</sub>                                   | $V_{GS} = -4 \text{ V}, \text{ I}_{D} = -5.5 \text{ A}$           | _          | 12   | 18   | mΩ   |
|   |               |  | $V_{GS} = -10 \text{ V}, \text{ I}_{D} = -5.5 \text{ A}$          | _          | 8.1  | 12   |      |
| Forward transfer admittance                               |               | Y <sub>fs</sub>  | $V_{DS} = -10 \text{ V}, \text{ I}_{D} = -5.5 \text{ A}$          | 11         | 23   | _    | S    |
| Input capacitance   |               | C <sub>iss</sub>                                       |   | _          | 5710 | _    |      |
| Reverse transfer capacitance                              |               | C <sub>rss</sub>                                       | $V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | _          | 560  |      | pF   |
| Output capacitance  |               | C <sub>oss</sub>                                       |   |            | 590  | _    |      |
|   | Rise time     | t <sub>r</sub>   | $V_{CS} = 0 V_{1} \Gamma_{D} = -5.5 A$                            | _          | 18   | _    |      |
| Switching time  | Turn-ON time  | $\begin{array}{c c c c c c c c c c c c c c c c c c c $ |   |            |      |      |      |
| Switching time  | Fall time     | t <sub>f</sub>   |   | _          | 109  |      | - ns |
|   | Turn-OFF time | t <sub>off</sub>                                       |   | _          | 396  |      |      |
| Total gate charge<br>(gate-source plus gate-drain)        |               | Qg   | Vpp ~ -24 V, Vpp - 10 V   |            | 107  |      | nC   |
| Gate-source charge 1                                      |               | Q <sub>gs1</sub>                                       |   |            | 12   | _    |      |
| Gate-drain ("miller") charge                              |               | Q <sub>gd</sub>  |   |            | 20   | _    |      |

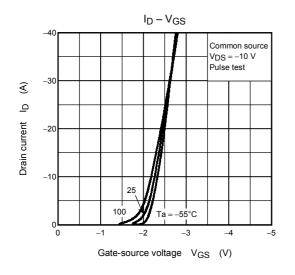
## Source-Drain Ratings and Characteristics (Ta = 25°C)

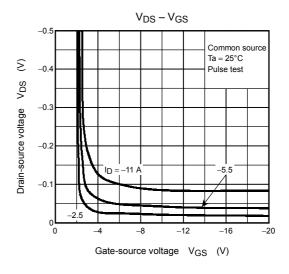
| Characteristics         |       | Symbol   | Test Condition   | Min  | Тур. | Max | Unit |   |
|-------------------------|-------|----------|------------------|--|------|-----|------|---|
| Drain reverse current   | Pulse | (Note 1) | I <sub>DRP</sub> | _  | _    | _   | -44  | А |
| Forward voltage (diode) |       |          | V <sub>DSF</sub> | $I_{DR} = -11 \text{ A}, V_{GS} = 0 \text{ V}$ |      |     | 1.2  | V |

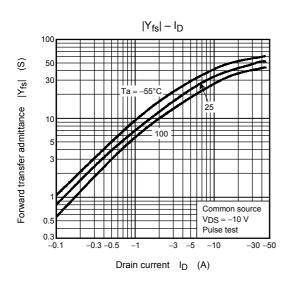
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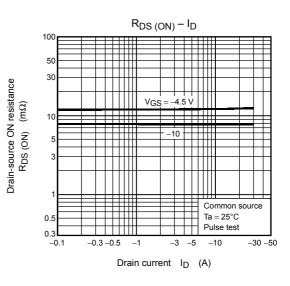




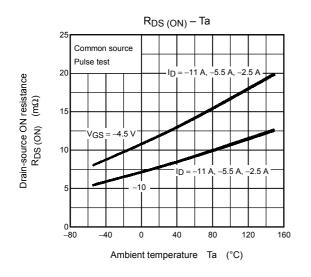


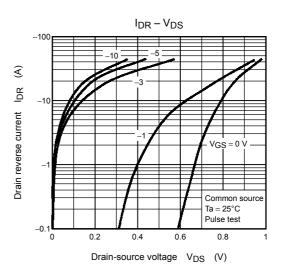




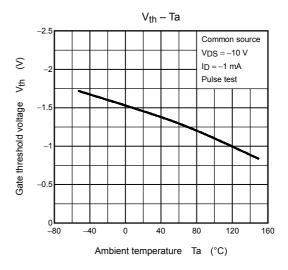


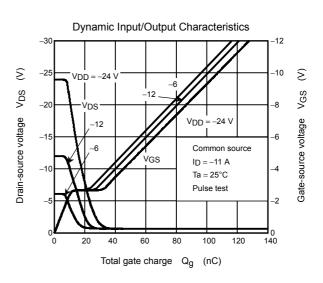
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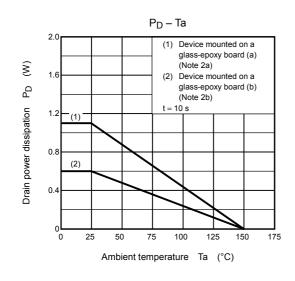


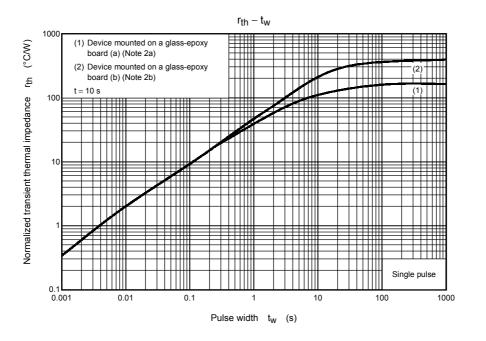


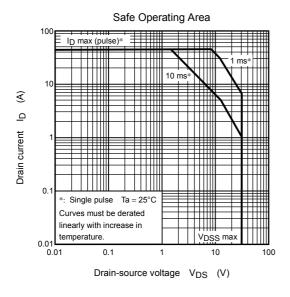
Capacitance - V<sub>DS</sub> 50000 30000 10000 (PF) 5000 ပ 3000 Capacitance 1000 500 Coss Crss Common source 300 VGS = 0 V f = 1 MHz  $\text{Ta}=25^\circ\text{C}$ 100 -0.3 -30 -0.1 -1 -3 -10 -100Drain-source voltage V<sub>DS</sub> (V)











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